

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

37. (Previously Presented) A method for forming an electronic circuit element, the method comprising:

providing a precursor element including a first insulating layer and a first conductor attached to said first insulating layer, said first insulating layer having a first surface, at least a portion of said first surface defining a first surface plane and said precursor element having a surface, said precursor element surface including said first surface of said first insulating layer;

placing a conducting member onto the precursor element and into electrical communication with said first conductor, said conducting member including a surface and protruding to an apex at a first level, said first level at least beyond said first surface plane;

said precursor element surface and said conducting member surface defining a major surface of a predetermined shape;

placing a second insulating layer including an adhesive onto substantially all of said major surface, said second insulating layer including oppositely disposed portions extending laterally from said conducting member along said first surface of said first insulating layer, said second insulating layer at said oppositely disposed portions extending to a second level, said first level beyond said second level; and

removing at least a portion of said second insulating layer proximate the apex of said conducting member.

38. (Currently Amended) An electronic circuit element comprising:

a first insulating layer having at least one surface, at least a portion of said surface defining a first surface plane;

at least one conductor along at least a portion of said at least one surface;

a ~~conducting member~~ solder bump in communication with said at least one conductor, said ~~conducting member~~ solder bump protruding to an apex at a first level, said first level beyond said

first surface plane, said ~~conducting member~~ solder bump including a surface; said surface of said first insulating layer, said at least one conductor, and said surface of said ~~conducting member~~ solder bump, defining a major surface of a predetermined shape;

a second insulating layer along at least a portion of said major surface whereby at least a portion of said ~~conducting member~~ solder bump is ~~remains~~ exposed, said second insulating layer including portions extending laterally from said ~~conducting member~~ solder bump along said first insulating layer, said laterally extending portions extending from said first surface plane to a second level, said second level ~~less than~~ not extending beyond said first level wherein said second insulating layer includes an adhesive.

39. (Currently Amended) The circuit of claim 38, wherein said exposed portion of said ~~conducting member~~ solder bump is proximate said apex.

40. (Canceled)

41. (Currently Amended) The circuit element of claim 38, wherein ~~said~~ at least a portion of said second insulating layer conforms to said predetermined shape of said major surface.

42. (Original) The circuit element of claim 41, wherein said laterally extending portions of said second insulating layer extend from said first surface plane to a second plane at said second level.

43. (Canceled)